ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATIONAL AND PARTICLE	C, Bannockl	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a decla the declaration	aration of on encon	of the subs mpasses al	stances w 11 lower	vithin the manufactule vel materials for v	urer listed	item. No nanufact	ote: if the turer has	item is an ass engineering r	embly with lower esponsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mfg Information				
Supplier Information																
Company name*	Company un	Company unique ID			Unique ID Authority					Respon	Response Date*					
onsemi												2023-06-08				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Representative			Phone - Representative*				Email -	Email - Representative*							
Product-Env-Stewards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective D	Date V	ersion	М	Manufacturing Site		Weight*	*	UOM	Unit Type	
	FODM8	801CR2	4SO HI-T TR T&R			2023-06-08	3		Tł	ТНН		74.267		mg	Each	
Manufacturing Proccess Informat	ion		1											1		
Terminal Plating / Grid Array Ma	terial	Ferminal Base	Alloy	J-STD-020 MS	L Rating	Peak Process B		Body Tem	ody Temperature Max Time at Peak		k Tempera	Temperature Numb		f Reflow Cycl	es	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		245		С		30 s		seconds 3				
Comments																
evel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds													
for more information regarding material	composition	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.267	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.0864	mg
			Supplier	Silicon (Si)	7440-21-3		0.1754	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0052	mg
Die Attach	0.25	mg	Supplier	Silver (Ag)	7440-22-4		0.205	mg
			Supplier	Dicyandiamine	461-58-5		0.0025	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0425	mg
Lead Frame	24.951	mg	Supplier	Silver (Ag)	7440-22-4		1.28	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0449	mg
			Supplier	Iron (Fe)	7439-89-6		0.6138	mg
			Supplier	Copper (Cu)	7440-50-8		22.9774	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0349	mg
Mold Compound-White	45.0	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		11.25	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		1.35	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.075	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.35	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		22.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.475	mg
Plating	0.239	mg	Supplier	Palladium (Pd)	7440-05-3		0.0095	mg
			В	Nickel (Ni)	7440-02-0		0.2238	mg
			Supplier	Gold (Au)	7440-57-5		0.0057	mg
Protective Coating	3.4	mg	Supplier	Poly(dimethylsiloxane), hydroxy terminated	70131-67-8		1.7	mg
			Supplier	Ethylbenzene	100-41-4		0.34	mg
			Supplier	Filler (SiO2)	68909-20-6		0.646	mg
			Supplier	Misc.	Proprietary Data		0.034	mg
			Supplier	Xylene	1330-20-7		0.68	mg
Wire Bond - Au	0.16	mg	Supplier	Gold (Au)	7440-57-5		0.16	mg